


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/18/10962	
1.3 Title of PCN	STM32L010x8/B and STM32L05/06/07/08 products Rousset 8" and Crolles CRL300	
1.4 Product Category	STM32L010x8/B and STM32L05/06/07/08 products	
1.5 Issue date	2018-11-12	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	MARCELI SMIALKOWSKI
2.1.2 Phone	+44 1628896277
2.1.3 Email	marceli.smialkowski@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	Rousset 8" Crolles CRL300

4. Description of change

	Old	New
4.1 Description	- Aluminium interconnect back end of line in Rousset 8".	- Aluminium interconnect back end of line in Rousset 8". - Copper interconnect back end of line in Rousset 8" and Crolles CRL300.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No change	

5. Reason / motivation for change

5.1 Motivation	To increase capacity
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability of the change is ensured by ST internal tools. No change on the marking or the labeling.
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7. Timing / schedule

7.1 Date of qualification results	2019-03-08
7.2 Intended start of delivery	2019-04-08
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	10962 MDG-MCD-RER1804 - PCN10962 - F9GO2S Technology Rou BEOL Alu to Copper _ RER1809 - PCN10962 - F9GO2S Technology Transfer to CR300 - Reliability Plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2018-11-12

9. Attachments (additional documentations)

10962 Public product.pdf
10962 MDG-MCD-RER1804 - PCN10962 - F9GO2S Technology Rou BEOL Alu to Copper _ RER1809 - PCN10962 - F9GO2S Technology
Transfer to CR300 - Reliability Plan.pdf
10962 PCN10962_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32L051K8T6	
	STM32L051K8U6	
	STM32L052T8Y6TR	
	STM32L071CBT6	
	STM32L071RZT6	
	STM32L071VZT6	
	STM32L072C6Y6TR	
	STM32L072VZI6	
	STM32L083CBT6	
	STM32L052C6T6	
	STM32L052K6U6	
	STM32L052K8U6	
	STM32L071CZT6	
	STM32L073VBT6	
	STM32L010K8T6	
	STM32L010RBT6	

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